



**THE DATASHEET OF
CIS21P300NE**



Chip Bead For High Current

CIS Series

APPLICATION

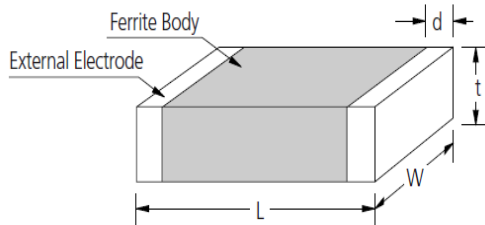
Noise Suppression in power line



FEATURES

- CIS series is used for high current. (~ 6A)

DIMENSION

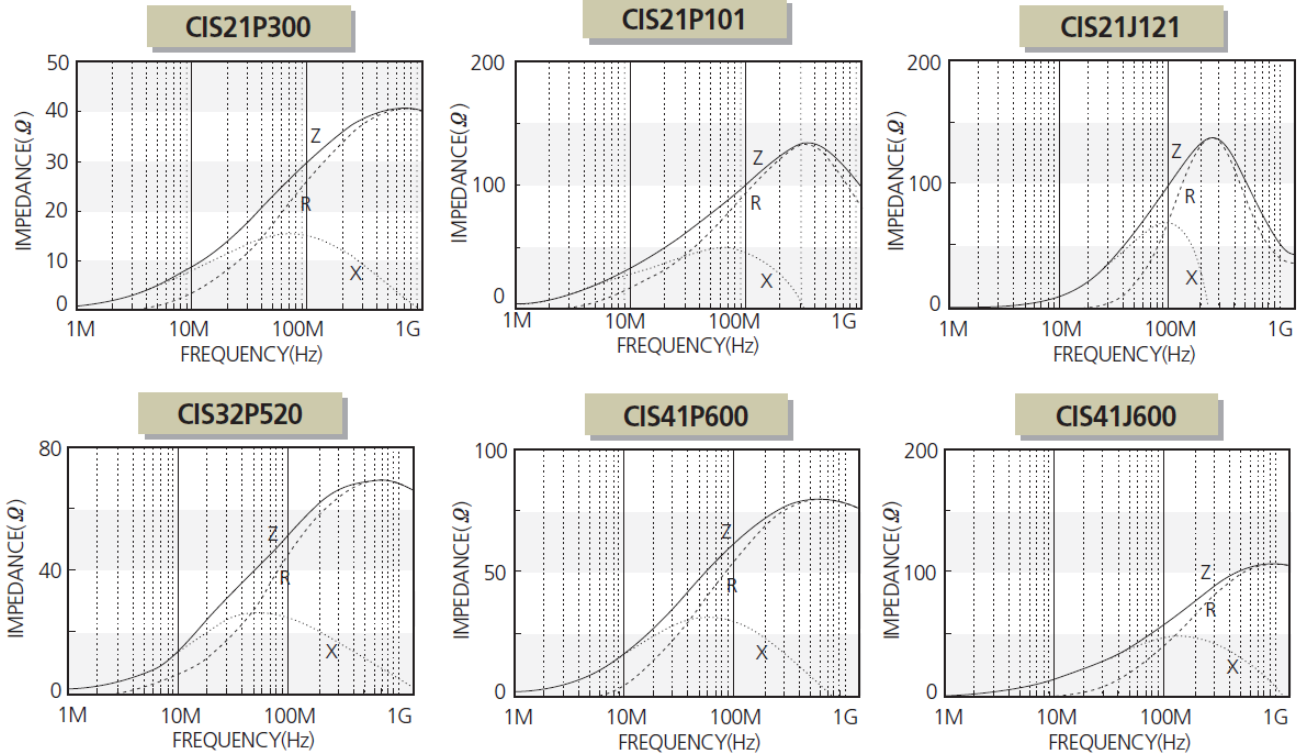


Type	Dimension [mm]			
	L	W	t	d
21	2.0±0.2	1.25±0.2	0.9±0.2	0.5+0.2 -0.3
32	3.2±0.2	2.5±0.2	1.3±0.2	0.5±0.3
41	4.5±0.2	1.6±0.2	N:1.6±0.2 A:1.2±0.2	0.5±0.3

DESCRIPTION

Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIS21P300	0.9±0.2	30	0.01	6000
CIS21P101	0.9±0.2	100	0.02	4000
CIS21J121	0.9±0.2	120	0.02	5000
CIS32P520	1.3±0.2	52	0.01	6000
CIS41P600	1.6±0.2/1.2±0.2	60	0.01	6000
CIS41J600	1.6±0.2/1.2±0.2	60	0.01	6000

CHARACTERISTIC DATA



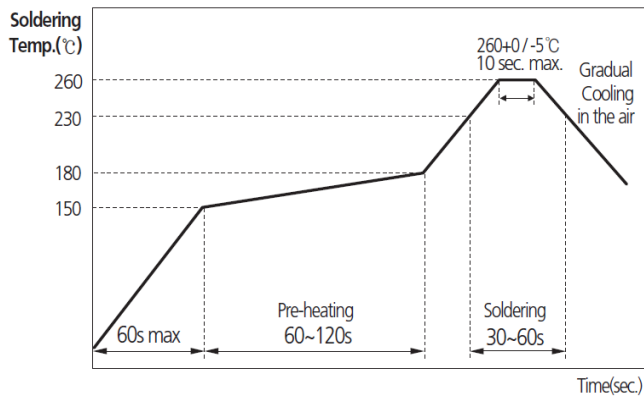
PRODUCT IDENTIFICATION

CI **S** **21** **P** **300** **N** **E**
(1) **(2)** **(3)** **(4)** **(5)** **(6)** **(7)**

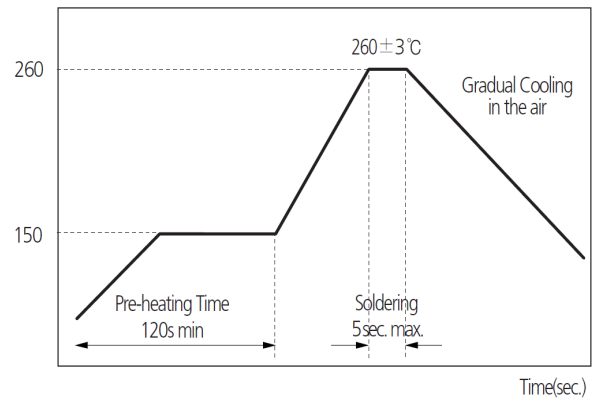
- (1) Chip Beads
- (2) For High current(S:~6A)
- (3) Dimension
- (4) Material Code
- (5) Nominal impedance (300:30Ω, 221:220Ω)
- (6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (7) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Type	Packaging Style	Quantity(pcs/reel)
21	Embossed Taping	4,000
32	Embossed Taping	2,500
41	Embossed Taping	2,000





Any data in this sheet are subject to change, modify or discontinue without notice.

The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.

Looking for pricing, stock, or lifecycle information?

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-  [Samsung Information](#)

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